

Abstract of the Disclosure:

An electronic component with an electronic circuit and electrical contacts, disposed at least on a first surface of the electronic component, for the electrical bonding of the electronic circuit includes at least one flexible elevation of an insulating material disposed on the first surface, at least one electrical contact disposed on the flexible elevation, and a conduction path disposed on the surface or in the interior of the flexible elevation between the electrical contact and the electronic circuit. A method for producing the electronic component is also provided.

GLM/kf

TOP SECRET